

3.2x1.6mm SMD CHIP LED LAMP

AP3216CGCK

GREEN

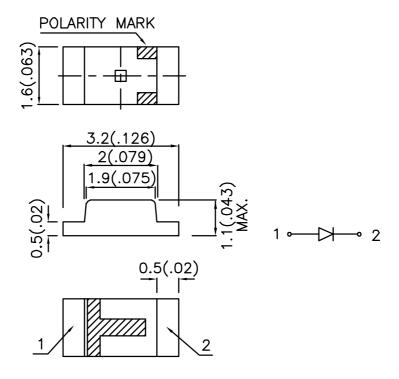
Features

- •3.2mmx1.6mm SMT LED, 1.1mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE: 2000PCS/REEL.
- •RoHS COMPLIANT.

Description

The Green source color devices are made with InGaAIP on GaAs substrate Light Emitting Diode.

Package Dimensions



- Notes: 1. All dimensions are in millimeters (inches). 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted. 3. Specifications are subject to change without notice.

SPEC NO: DSAA6052 **REV NO: V.5** APPROVED: J. Lu **CHECKED: Allen Liu** DATE: MAR/15/2005 DRAWN: W.J.ZHU

PAGE: 1 OF 4 ERP:1203000333

Kingbright

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle
			Min.	Тур.	2 θ 1/2
AP3216CGCK	GREEN (InGaAIP)	WATER CLEAR	10	40	120°

Note:

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	574		nm	IF=20mA
λD	Dominant Wavelength	Green	570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	20		nm	IF=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF	Forward Voltage	Green	2.1	2.5	V	IF=20mA
IR	Reverse Current	Green		10	uA	VR = 5V

Absolute Maximum Ratings at Ta=25°C

Parameter	Green	Units	
Power dissipation	105	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		

Note:

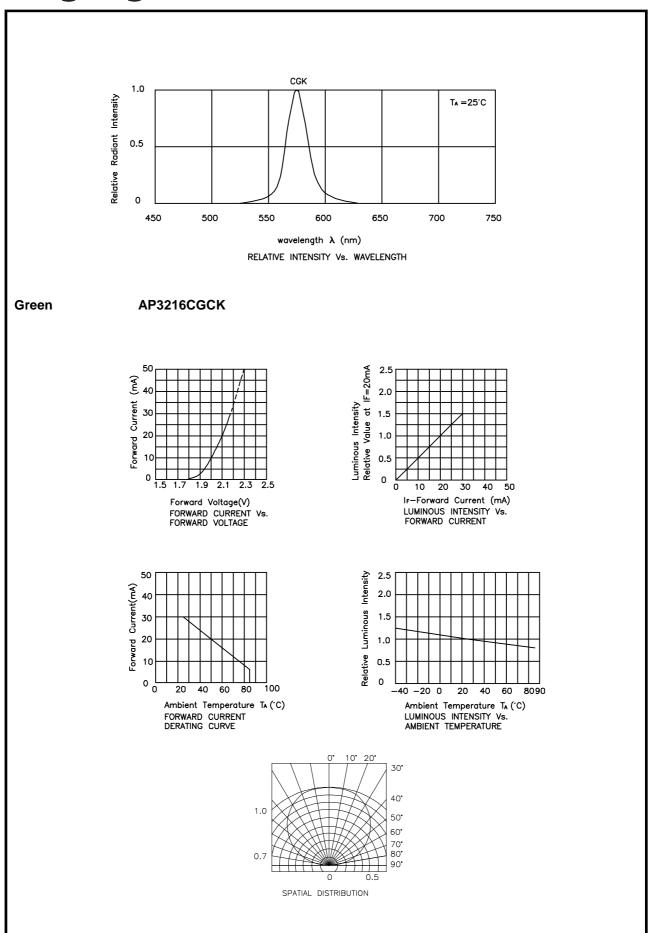
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

 SPEC NO: DSAA6052
 REV NO: V.5
 DATE: MAR/15/2005
 PAGE: 2 OF 4

 APPROVED: J. Lu
 CHECKED: Allen Liu
 DRAWN: W.J.ZHU
 ERP:1203000333

 $^{1.\,\}theta1/2$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Kingbright



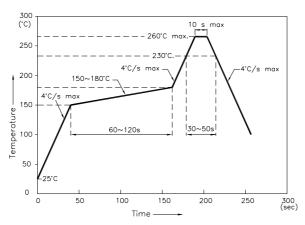
 SPEC NO: DSAA6052
 REV NO: V.5
 DATE: MAR/15/2005
 PAGE: 3 OF 4

 APPROVED: J. Lu
 CHECKED: Allen Liu
 DRAWN: W.J.ZHU
 ERP:1203000333

Kingbright

AP3216CGCK

Reflow Soldering Profile For Lead-free SMT Process.



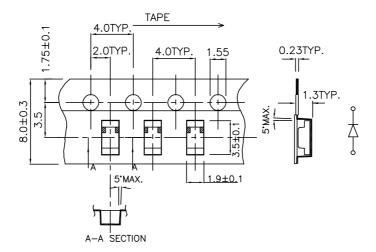
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
 - 2.Don't cause stress to the epoxy resin while it $% \left(1\right) =\left(1\right) +\left(1\right) =\left(1\right) =\left(1\right) +\left(1\right) =\left(1\right) =\left(1\right) +\left(1\right) =\left(1\right) =\left$ to high temperature.
 - 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage,luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

REV NO: V.5 SPEC NO: DSAA6052 DATE: MAR/15/2005 PAGE: 4 OF 4 APPROVED: J. Lu CHECKED: Allen Liu DRAWN: W.J.ZHU ERP:1203000333